



Product Change Notification

Change Notification #: 116532 - 00
Change Title: Intel® 8x2.5" Hot Swap PCIe NVMe SFF COMBO Drive Bay Kit AUP8X25S3NVDK PCN 116532-00, Product Design, Hot Swap Back Plane Firmware Update
Date of Publication: October 09, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:*	October 25, 2018
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*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is updating the Hot Swap Back Plane (HSBP) Firmware on the Intel® 8x2.5" Hot Swap PCIe NVMe SFF COMBO Drive Bay Kit AUP8X25S3NVDK as listed in the "Products Affected" table below. PSOC FW 2.84 is the new version installed from Factory.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Customers can download and evaluate the PSOC Firmware Release integrated in the latest BIOS/ME/Integrated BMC and FRUSDR package posted at <http://www.intel.com/support>.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
AUP8X25S3NVDK	953393	J21195-001	H88386-250	J21195-002	H88386-251

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 09, 2018	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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